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## Getting Started with the AD-DAC-FMC-ADP Adapter Board

## INTRODUCTION

The ADC-DAC-FMC-ADP adapter board allows any of Analog Devices' DPG2-compatiable High-Speed DAC Evaluation Boards to be used on a Xilinx evaluation board with a FMC connector. The adapter board uses the Low Pin Count (LPC) version of the FMC connector, so it can be used on either LPC or HPC hosts (such as the ML605 or SP605).

A list of DPG2-compatiable evaluation boards can be found at http://www.analog.com/dpg

The schematic and layout are included in the following pages of this document. In addition, example UCF files for both the ML605 and SP605 are included as a starting point.

## CLOCKING

Every DPG2-compatiable evaluation board provides two LVDS clocks to the host. These two clocks are always identical in both frequency and phase. On DACs using an LVDS interface, the host is then expected to output two LVDS clocks that are phase aligned to the data. It is very important that these clocks be generated the same way as the data, so that any delays inside the FPGA are matched. Therefore, this clock should be considered another data bit with a fixed "10101" pattern.





PRIMARY SIDE
notes:
MATERIALS;
Fr-4, in ACCORDANCE WITH IPC-L-130 (LATEST REV.). GLASS FABRIC
bonding agent; PREIMPREGNATED B STAGE EPOXY GLASS Cloth in accordance with
Claddinge ipc-L-109 (Latest rev.).
CLADDING; EXTERNAL LAYERS $1 / 40 Z$, COPPER, OVERPLATE TO 102.
SOLDER MASK: SHALL BE BLUE LIOUID PHOTOIMAGABLE (LPI) APPLIED ON BOTH SIDES OVER SILK SCREEN: BARE COPPER AND SHALL MEET IPC-SM-840 (LATEST REV.) CLASS 3
$\begin{array}{ll}\text { SILK SCREEN; } & \text { SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK, COLOR WHITE. } \\ \text { U.L. RATING; } & \text { 94VO MINIMUM. }\end{array}$
fabrication:
REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 for fabrication unless OTHERWISE SPECIFIED.
2. Undimensioned holes to be located within +/-.005 of their true position
3. PLATED HOLE WALL THICKNESS Shall NOT be Less than . 001 inch minimum

AVERAGE, WITH NO READING LESS THAN. 0008 BY CROSS SECTION.
4. HOLE DIAM CONDUCTOR WIDTHS SHALL NOT be REDUCED FROM THE NOMINAL
indicated on the master pattern, by more than the conductor thickness.
6. MINIMUM DESIGN LINE WIDTH IS . 008 INCH.
8. MINIMUM DESIGN SPACING 1 BOARD/PANEL MUST MEET IPC-A-600 (LATEST REV.) CLASS 2 FOR FLATNESS MFGR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE IN on secondary side in a clear area unless otherwise indicated;
A. U.L. CODE
B. DATE CODE (STAMP)

E
E. succissfu electrical boato test.
B. DATE CODE (STAMP)
be removed from inner signal layers at mfgr.
10. Non-functional pads mar be remone
11. IF PAD Sizes provided are not large enough to maintain annular ring REQUIREMENT, MFGR. MAY TEAR DROP PADS TO MAINTAIN ANNULAR RING AT PAD
12. REPAIRS PER IPC-R-700 ARE ALLOWED.
13. MODIFICATIONS TO THE ARTWORK, OTHER THAN THOSE DESCRIbED ON THE 14. FABRICATION DRAWING, ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
FINISH: SURFACES SHALL HAVE ENI FIIISH PLATE WIT 2-6 MIROINCHES OF
IMMERSION GOLD OVER $100-200$ MICROINCHES OF ELECTROLESS NICKEL.

| hole Tolerance |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
| UNLESS SPECIFIED <br> PLATED: + - . 003 NON PLATED: + / . . 001 |  |  |  |  |
| FINISHED HOLES IN MILS |  |  |  |  |
| ALL UNITS ARE IN MILS |  |  |  |  |
| FIGURE | SIZE | PLATED | QTY | TOLERANCE/NOTES |
| + | 10.0 | PLATED | 162 |  |
| - | 24.0 | PLATED | 120 |  |
| A | 50.0 | NON-PLATED | 2 |  |
| B | 105.0 | NON - PLATED | 2 |  |








$$
\begin{gathered}
\text { SOLDERMASK PRIMARY } \\
\text { (4) VITA57-DPG2 ADAPTER BRD } \\
\text { HSC } 10033 \\
\text { REV A }
\end{gathered}
$$






